

# TOSHIBA MOS MEMORY PRODUCT

16,384 WORD X 4 BIT CMOS STATIC RAM  
SILICON GATE CMOS

TC55417P-35  
TC55417P-45

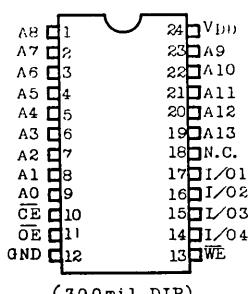
## DESCRIPTION

The TC55417P is a 65,536 bit high speed static random access memory organized as 16,384 words by 4 bits using CMOS technology, and operated from a single 5-volt supply. Toshiba's high performance device technology provides both high speed and low power features with a maximum access time of 35ns/45ns and maximum operating current of 80mA/60mA at minimum cycle time. The TC55417P also features an automatic stand-by mode. When deselected by Chip Enable ( $\overline{CE}$ ), the operating current is reduced to 10mA. The TC55417P is suitable for use in cache memory and high speed storage, where high speed/high density are required. The TC55417P is molded in a 24 pin standard plastic package with 0.3 inch width for high density assembly. The TC55417P is fabricated with ion implanted CMOS silicon gate MOS technology for high performance and high reliability.

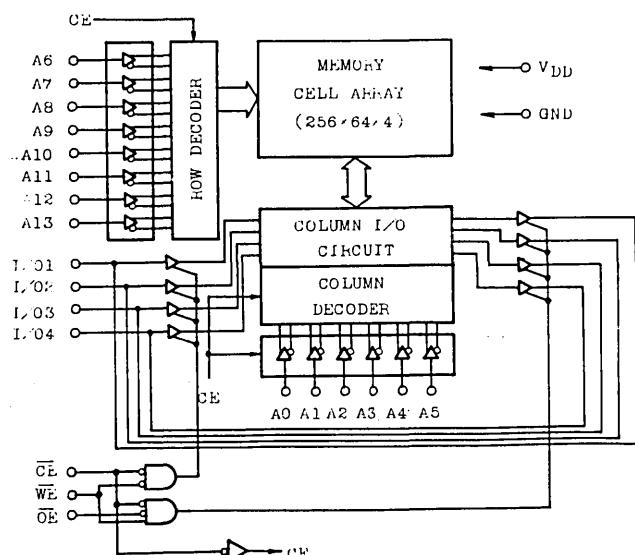
## FEATURES

- Fast access time : TC55417P-35 35ns (Max.)  
TC55417P-45 45ns (Max.)
- Low power dissipation: Operation TC55417P-35 80mA (Max.)  
TC55417P-45 60mA (Max.)  
Standby 10mA (Max.)
- 5V single power supply
- Fully static operation
- Directly TTL compatible: All Input and Output
- Output buffer control :  $\overline{OE}$
- Package : 24 pins standard plastic package, 300 mil width.

## PIN CONNECTION



## BLOCK DIAGRAM



## PIN NAMES

A0 ~ A13	Address Inputs
I/O1 ~ I/O4	Data Input/Output
$\overline{CE}$	Chip Enable Input
WE	Write Enable Input
$\overline{OE}$	Output Enable Input
VDD	Power (+5V)
GND	Ground
N.C.	No Connection

**TC55417P-45**

**MAXIMUM RATINGS**

SYMBOL	ITEM	RATING	UNIT
$V_{DD}$	Power Supply Voltage	-0.3 ~ 7.0	V
$V_{IN}$	Input Voltage	-2.0 ~ 7.0	V
$V_{OUT}$	Output Voltage	-0.5 ~ $V_{DD}+0.5$	V
$P_D$	Power Dissipation	650	mW
$T_{solder}$	Soldering Temperature • Time	260 • 10	°C•sec
$T_{stg}$	Storage Temperature	-65 ~ 150	°C
$T_{opr}$	Operating Temperature	0 ~ 70	°C

**D.C. RECOMMENDED OPERATING CONDITIONS**

SYMBOL	PARAMETER	MIN.	TYP.	MAX.	UNIT
$V_{DD}$	Power Supply Voltage	4.5	5.0	5.5	V
$V_{IH}$	Input High Voltage	2.2	-	$V_{DD}+0.3$	V
$V_{IL}$	Input Low Voltage	-0.3	-	0.8	V

**D.C. and OPERATING CHARACTERISTICS (Ta=0 ~ 70°C,  $V_{DD}=5V\pm10\%$ )**

SYMBOL	PARAMETER	TEST CONDITION			MIN.	TYP.	MAX.	UNIT
$I_{IL}$	Input Leakage Current	$V_{IN}=0 \sim V_{DD}$			-	-	$\pm 1.0$	$\mu A$
$I_{OH}$	Output High Current	$V_{OH}=2.4V$			-4	-	-	mA
$I_{OL}$	Output low Current	$V_{OL}=0.4V$			8	-	-	mA
$I_{LO}$	Output Leakage Current	$\overline{CE}=V_{IH}$ or $\overline{WE}=V_{IL}$ $V_{OUT}=0 \sim V_{DD}$			-	-	$\pm 1.0$	$\mu A$
$I_{DDO}$	Operating Current	$V_{DD}=5.5V$ $t_{cycle}=\text{Min cycle}$ $\overline{CE}=V_{IL}$ Other Input= $V_{IH}/V_{IL}$	$-35$	-	-	80	mA	
			$-45$	-	-	60		
$I_{DDS1}$	Standby Current	$V_{DD}=5.5V$ , $t_{cycle}=\text{Min cycle}$ $\overline{CE}=V_{IH}$ , Other Input= $V_{IH}/V_{IL}$	-	-	-	20	mA	
$I_{DDS2}$		$\overline{CE}=V_{DD}-0.2V$ Other Input= $V_{DD}-0.2V$ or $0.2V$	-	-	-	1		

**CAPACITANCE (Ta=25°C)**

SYMBOL	PARAMETER	TEST CONDITION	MAX.	UNIT
$C_{IN}$	Input Capacitance	$V_{IN}=GND$	10	pF
$C_{OUT}$	Output Capacitance	$V_{OUT}=GND$	10	pF

Note: This parameter periodically sampled is not 100% tested.

A.C. CHARACTERISTICS (Ta=0 ~ 70°C, V<sub>DD</sub>=5V±10%)

Read Cycle

SYMBOL	PARAMETER	TC55417P-35		TC55417P-45		UNIT
		MIN.	MAX.	MIN.	MAX.	
t <sub>RC</sub>	Read Cycle Time	35	-	45	-	ns
t <sub>ACC</sub>	Address Access Time	-	35	-	45	ns
t <sub>CO</sub>	Chip Enable Access Time	-	35	-	45	ns
t <sub>OE</sub>	Output Enable to Output Valid	-	20	-	20	ns
t <sub>COE</sub>	Chip Enable to Output in Low-Z	0	-	0	-	ns
t <sub>COD</sub>	Chip Enable to Output in High-Z	-	15	-	20	ns
t <sub>OEE</sub>	Output Enable to Output in Low-Z	0	-	0	-	ns
t <sub>ODO</sub>	Output Disable to Output in High-Z	-	15	-	15	ns
t <sub>OH</sub>	Output Data Hold Time	5	-	5	-	ns

Write Cycle

SYMBOL	PARAMETER	TC55417P-35		TC55417P-45		UNIT
		MIN.	MAX.	MIN.	MAX.	
t <sub>WC</sub>	Write Cycle Time	35	-	45	-	ns
t <sub>WP</sub>	Write Pulse Width	30	-	35	-	ns
t <sub>CW</sub>	Chip Enable to End of Write	30	-	35	-	ns
t <sub>AS</sub>	Address Set Up Time	0	-	0	-	ns
t <sub>WR</sub>	Write Recovery Time	0	-	0	-	ns
t <sub>ODW</sub>	WE to Output High-Z	-	15	-	15	ns
t <sub>OEW</sub>	WE to Output Low-Z	0	-	0	-	ns
t <sub>DS</sub>	Data Set Up Time	15	-	20	-	ns
t <sub>DH</sub>	Data Hold Time	0	-	0	-	ns

A.C. TEST CONDITIONS

Input Pulse Levels	0.6V, 2.4V
Input Rise and Fall Time	5ns
Input and Output Timing Reference Levels	0.8V, 2.0V
Output Load	See Fig. 1

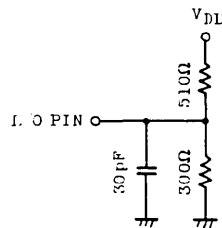
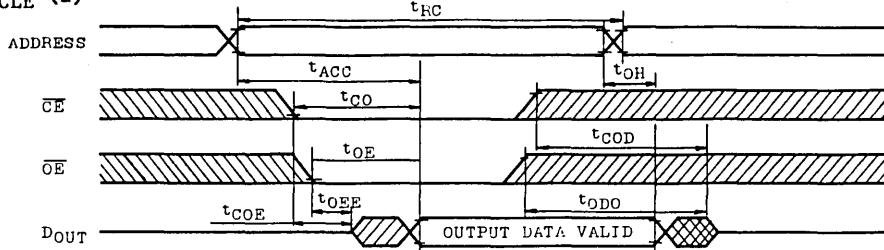


Fig. 1 OUTPUT LOAD

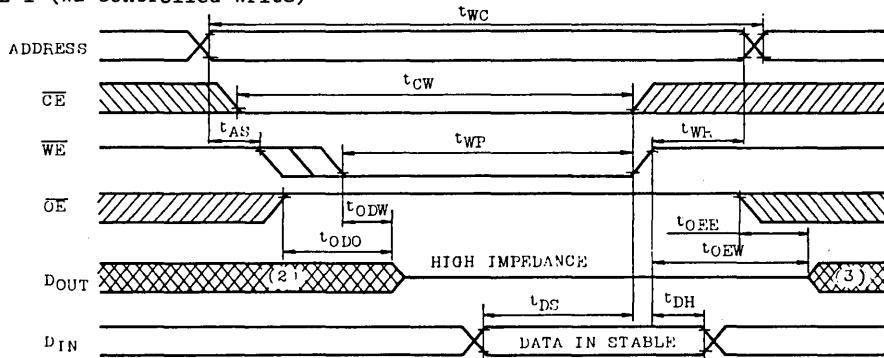
Note: In all condition, t<sub>COD</sub> max is less than t<sub>COE</sub> min both for a given device and from device to device.

TIMING WAVEFORMS

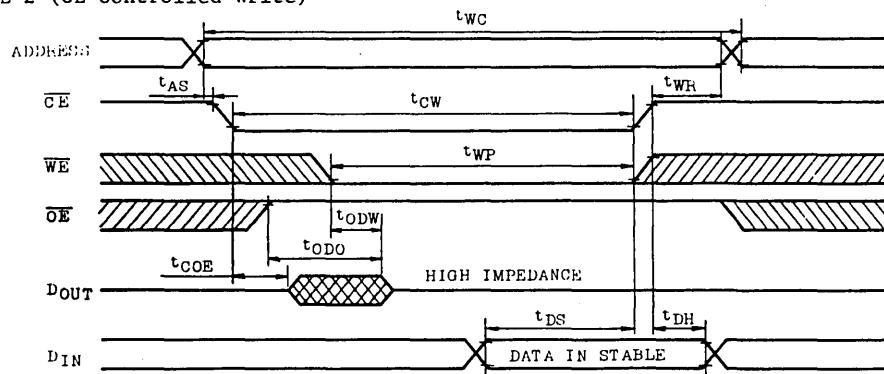
READ CYCLE (1)



WRITE CYCLE 1 ( $\overline{WE}$  Controlled Write)



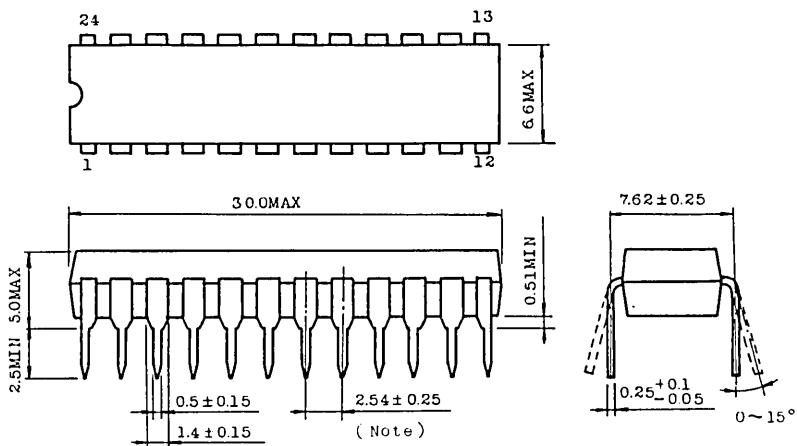
WRITE CYCLE 2 ( $\overline{CE}$  Controlled Write)



- Note:
1.  $\overline{WE}$  is High for Read cycle.
  2. Assuming that  $\overline{CE}$  Low transition occurs coincident with or after  $\overline{WE}$  Low transition, Outputs remain in a high impedance state.
  3. Assuming that  $\overline{CE}$  High transition occurs coincident with or prior to  $\overline{WE}$  High transition, Outputs remain in a high impedance state.
  4. The Operating temperature ( $T_a$ ) is guaranteed with transverse air flow exceeding 400 linear feet per minute.

OUTLINE DRAWINGS

Unit in mm



Note: Each lead pitch is 2.54mm.

All leads are located within 0.25mm of the true longitudinal position with respect to No.1 and No.24 leads.